

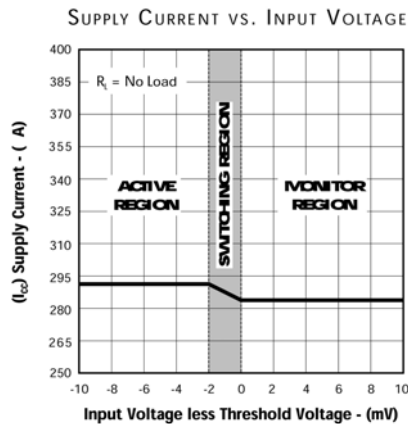
DESCRIPTION

The MC34064 is an undervoltage sensing circuit designed specifically for use as a reset controller in microprocessor-based systems. It offers the designer an economical, space-efficient solution for low supply voltage detection when used in combination with a single pullup resistor. Adding one capacitor offers the functionality of a programmable delay time after power returns. The MC34064 consists of a temperature stable reference comparator with hysteresis, high-current clamping diode and open collector output stage capable of sinking up to 60mA. The MC34064's RESET output is specified to be fully functional at $V_{IN}=1V$. A major improvement over competing products is the glitch-free supply current during undervoltage detection. Competing products demand a step function increase in operating current during the time that you least want or need it: during power loss. See Product Highlight below.

IMPORTANT: For the most current data, consult MICROSEMI's website: <http://www.microsemi.com>

KEY FEATURES

- Monitors 5V Supplies ($V_T = 4.6V$ Typ.)
- Outputs Fully Defined At $V_{IN} = 1V$ (See Figure 1)
- Glitch-Free Supply Current During Switching (See Product Highlight)
- Ultra-Low Supply Current (500 μA Max.)
- Temperature Compensated ICC For Extremely Stable Current Consumption
- μP Reset Function Programmable With 1 External Resistor And Capacitor
- Comparator Hysteresis Prevents Output Oscillation
- Electrically Compatible With Motorola MC34064
- Pin-to-Pin Compatible With Motorola MC34064 / MC34164

PRODUCT HIGHLIGHT

APPLICATIONS

- All Microprocessor Or Microcontroller Designs Using 5V Supplies
- Simple 5V Undervoltage Detection

PACKAGE ORDER INFO

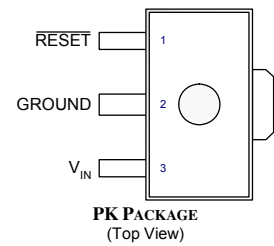
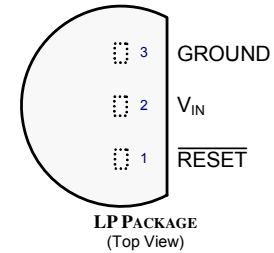
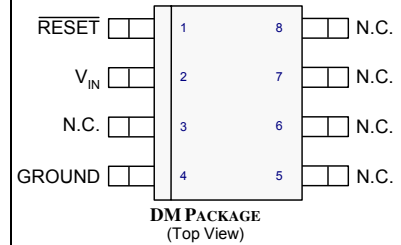
| T_A ($^{\circ}C$) | DM Plastic SOIC 8-Pin | LP Plastic TO-92 3-Pin | PK Plastic SOT-89 3-Pin |
|-----------------------|---------------------------------------|---------------------------------------|---------------------------------------|
| | RoHS / Pb-free Transition DC: 0440 | RoHS / Pb-free Transition DC: 0509 | RoHS / Pb-free Transition DC: 0518 |
| 0 to 70 | MC34064DM | MC34064LP | MC34064PK |
| -40 to 85 | MC33064DM | MC33064LP | MC33064PK |

Note: Available in Tape & Reel. Append the letters "TR" to the part number. (i.e. LX34064DM-TR)

Undervoltage Sensing Circuit
PRODUCTION DATA SHEET
ABSOLUTE MAXIMUM RATINGS

| | |
|--|-------------------------|
| Input Supply Voltage (V_{IN})..... | -1V to 10V |
| RESET Output Voltage (V_{OUT})..... | 10V |
| Output Sink Current (I_{OL})..... | Internally Limited (mA) |
| Clamp Diode Forward Current (I_F), Pin 1 to Pin 2..... | 100mA |
| Operating Temperature Range..... | 150°C |
| Operating Ambient Temperature Range (T_A) | |
| MC34064 | 0°C to 70°C |
| MC33064 | -40°C to 85°C |
| Storage Temperature Range..... | -65°C to 150°C |
| Package Peak Temp. for Solder Reflow (40 seconds maximum exposure) ... | 260°C (+0 -5) |

Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

PACKAGE PIN OUT


RoHS / Pb-free 100% matte Tin Lead Finish

THERMAL DATA
DM Plastic SOIC 8-Pin

| | |
|---|----------------|
| THERMAL RESISTANCE-JUNCTION TO AMBIENT, θ_{JA} | 165°C/W |
|---|----------------|

LP Plastic TO-92 3-Pin

| | |
|---|----------------|
| THERMAL RESISTANCE-JUNCTION TO AMBIENT, θ_{JA} | 156°C/W |
|---|----------------|

PK Plastic SOT-89 3-Pin

| | |
|---|---------------|
| THERMAL RESISTANCE-JUNCTION TO TAB, θ_{JT} | 35°C/W |
| THERMAL RESISTANCE-JUNCTION TO AMBIENT, θ_{JA} | 71°C/W |

Junction Temperature Calculation: $T_J = T_A + (P_D \times \theta_{JA})$.

The θ_{JA} numbers are guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.

RECOMMENDED OPERATING CONDITIONS

Conditions: Range over which the device is functional.

| Parameter | Symbol | MC3x064 | | | Units |
|-----------------------------|-----------|---------|-----|-----|-------|
| | | Min | Typ | Max | |
| Input Supply Voltage | V_{IN} | 1 | | 6.5 | V |
| RESET Output Voltage | V_{OUT} | | 6.5 | | V |
| Clamp Diode Forward Current | I_F | | 50 | | mA |

IC ELECTRICAL CHARACTERISTICS

Unless otherwise specified, the following specifications apply over the operating ambient temperature $0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$ for the MC34064 and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ for the MC33064. Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.

| Parameter | Symbol | Test Conditions | MC3x064 | | | Units |
|-------------------------------------|----------|--|---------|------|------|---------------|
| | | | Min | Typ | Max | |
| COMPARATOR SECTION | | | | | | |
| Threshold Voltage | | | | | | |
| High State Output | V_{T+} | V_{IN} Increasing – 4V to 5V | 4.5 | 4.61 | 4.7 | V |
| Low State Outputs | V_{T-} | V_{IN} Decreasing – 5V to 4V | 4.5 | 4.59 | 4.7 | V |
| Hysteresis | V_H | | 0.01 | 0.02 | 0.05 | V |
| RESET OUTPUT SECTION | | | | | | |
| Output Low Level Saturation Voltage | V_{OL} | $V_{IN} = 4.0\text{V}$, $I_{OL} = 8.0\text{mA}$ | | | 1.0 | V |
| | | $V_{IN} = 4.0\text{V}$, $I_{OL} = 2.0\text{mA}$ | | | 0.4 | V |
| | | $V_{IN} = 1.0\text{V}$, $I_{OL} = 0.1\text{mA}$ | | | 0.1 | V |
| Output Low Level Current | I_{OL} | $V_{IN} = V_{OUT} = 4.0\text{V}$ | 10 | 27 | 60 | mA |
| Output Off-State Leakage | I_{OH} | $V_{IN} = V_{OUT} = 5.0\text{V}$ | | 0.02 | 0.5 | μA |
| Clamp Diode Forward Voltage | V_F | Pin 1 to Pin 2, $I_F = 10\text{mA}$ | 0.6 | 0.9 | 1.2 | V |
| TOTAL DEVICE | | | | | | |
| Supply Current | I_{CC} | $V_{IN} = 5.0\text{V}$ | | 390 | 500 | μA |

CHART AND APPLICATION INDEX
Characteristic Curves

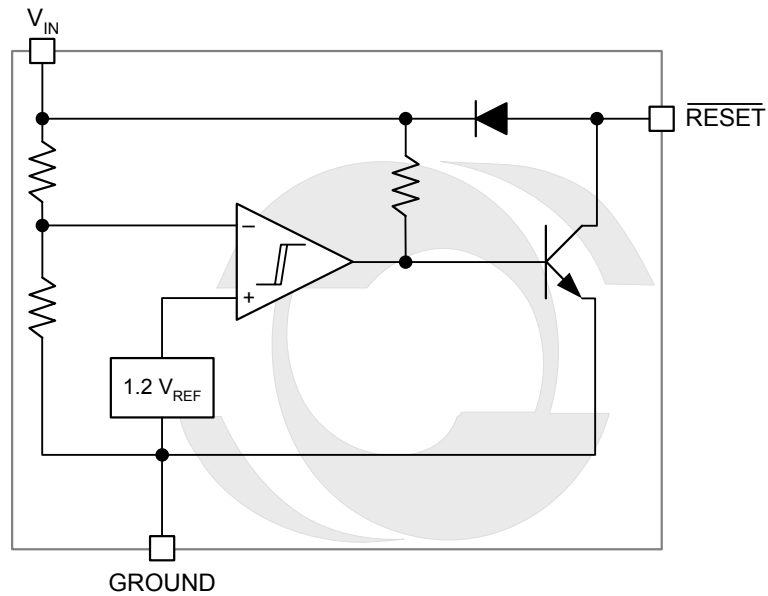
- Figure #
1. Input Voltage and $\overline{\text{RESET}}$ Output Voltage vs. Time
 2. Power-Up $\overline{\text{RESET}}$ Voltage
 3. Power-Down $\overline{\text{RESET}}$ Voltage
 4. $\overline{\text{RESET}}$ Output Voltage vs. Input Voltage
 5. Threshold Voltage vs. Temperature
 6. Threshold Hysteresis vs. Temperature
 7. Supply Current vs. Input Voltage
 8. Supply Current vs. Temperature
 9. Low Level Output Current vs. Temperature
 10. Low Level Output Saturation Voltage vs. Temperature
 11. Low Level Output Saturation Voltage vs. Temperature
 12. Clamp Diode Forward Voltage vs. Forward Current
 13. Propagation Delay – HIGH to LOW
 14. Propagation Delay – LOW to HIGH

Application Circuits

- Figure #
15. Low Voltage Microprocessor Reset
 16. Switching the Load off when Battery Reaches Below 4.3V
 17. Voltage Monitor
 18. MOSFET Low Voltage Gate Drive Protection
 19. Low Voltage Microprocessor Reset with Additional Hysteresis
 20. Solar Powered Battery



SIMPLIFIED BLOCK DIAGRAM



Simplified Block Diagram



CHARACTERISTIC CURVES

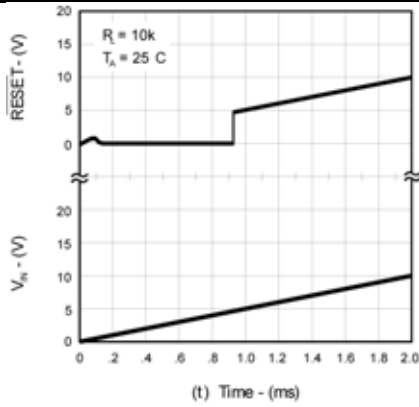


Figure 1 – Input Voltage and $\overline{\text{RESET}}$ Output Voltage vs. Time

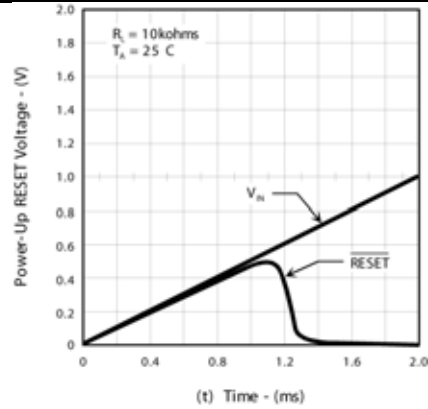


Figure 2 – Power-Up $\overline{\text{RESET}}$ Voltage

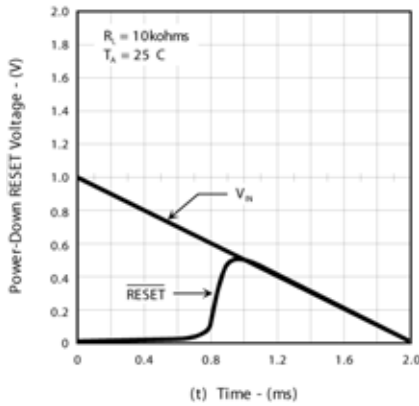


Figure 3 – Power-Down $\overline{\text{RESET}}$ Voltage

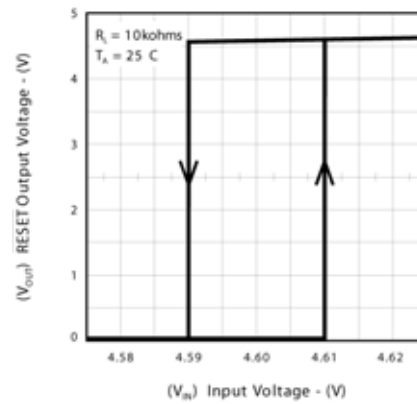


Figure 4 – $\overline{\text{RESET}}$ Output Voltage vs. Input Voltage

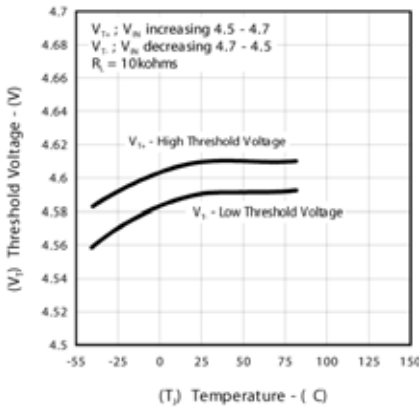


Figure 5 – Threshold Voltage vs. Temperature

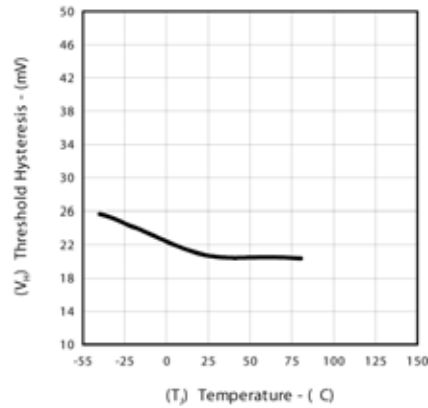


Figure 6 – Threshold Hysteresis vs. Temperature



CHARACTERISTIC CURVES

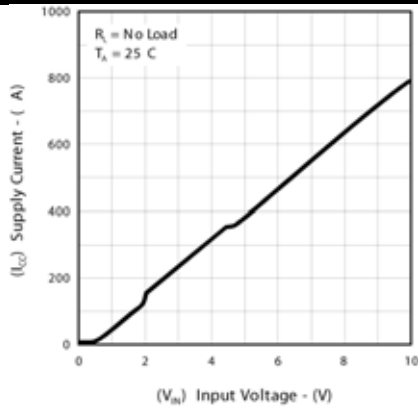


Figure 7 – Supply Current vs. Input Voltage

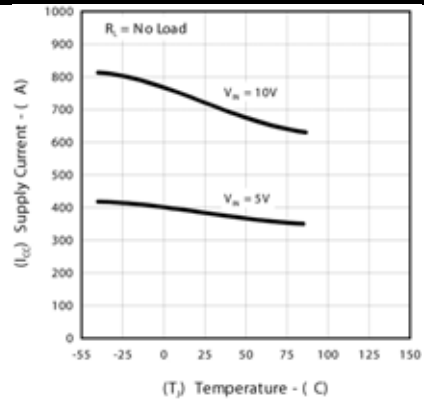


Figure 8 – Supply Current vs. Temperature

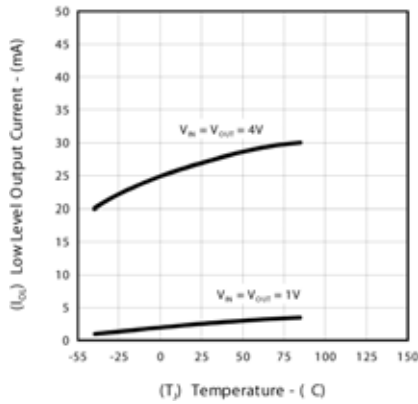


Figure 9 – Low Level Output Current vs. Temperature

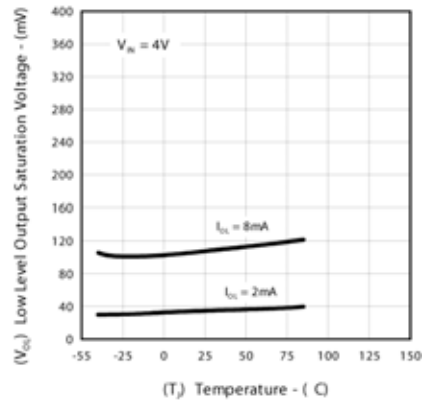


Figure 10 – Low Level Output Saturation Voltage vs. Temperature

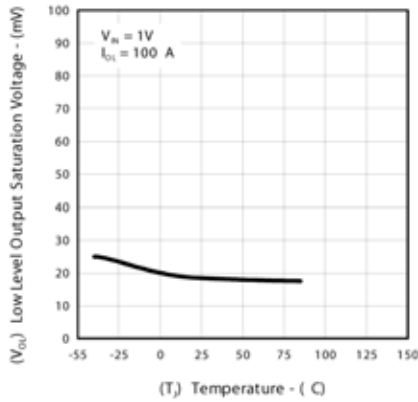


Figure 11 – Low Level Output Saturation Voltage vs. Temperature

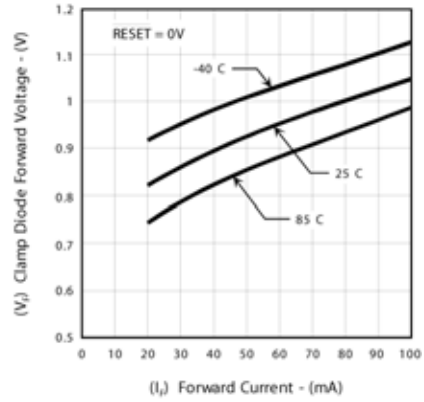
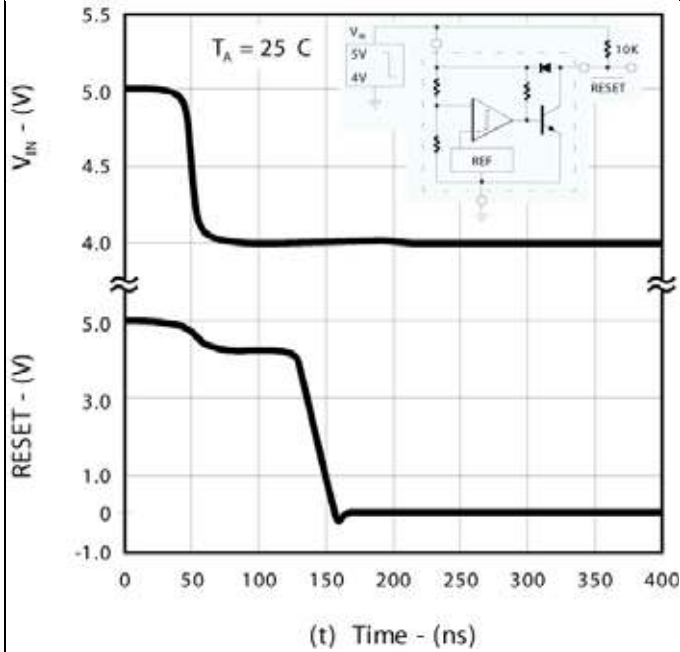
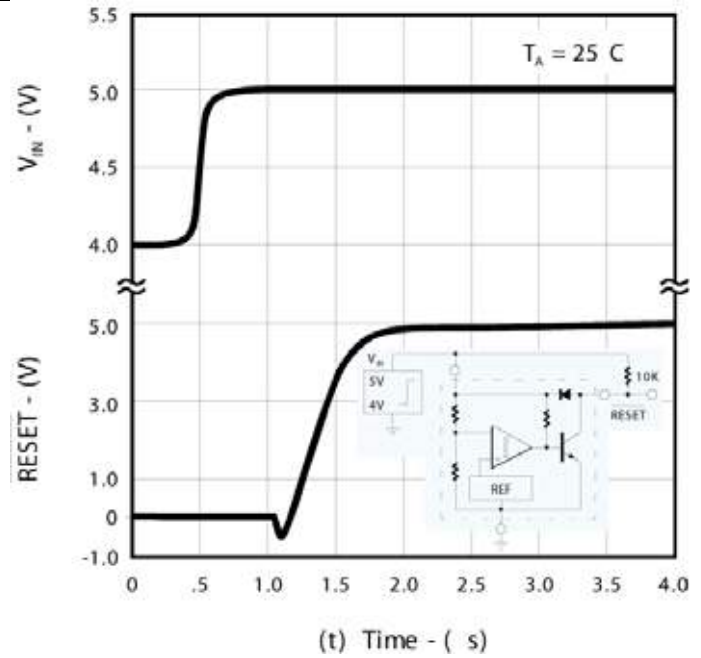


Figure 12 – Clamp Diode Forward Voltage vs. Forward Current

CHARACTERISTIC CURVES

Figure 13 – Propagation Delay – HIGH to LOW

Figure 14 – Propagation Delay – LOW to HIGH



TYPICAL APPLICATION CIRCUITS

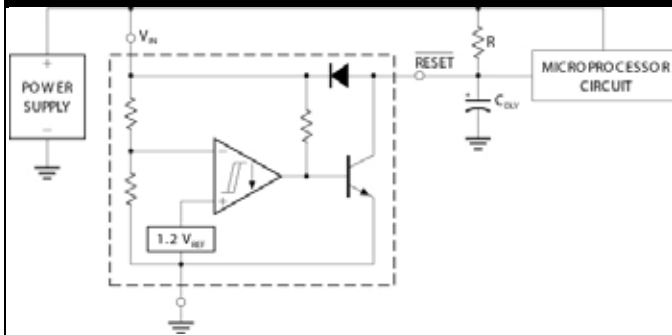


Figure 15 – Low Voltage Microprocessor Reset

A time delayed reset can be accomplished with the addition of C_{DLY} . For systems with extremely fast power supply rise times (<500ns) it is recommended that the RC_{DLY} time constant be greater than $5.0\mu s$. $V_{TH(MPU)}$ is the microprocessor reset input threshold.

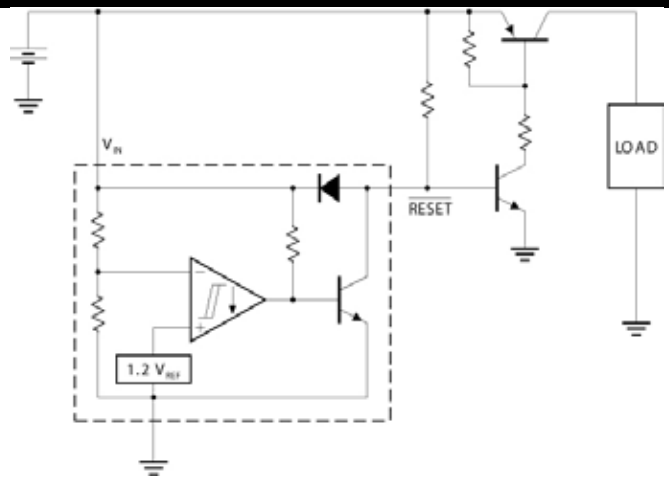


Figure 16 – Switching the Load off When battery Reaches Below 4.3V

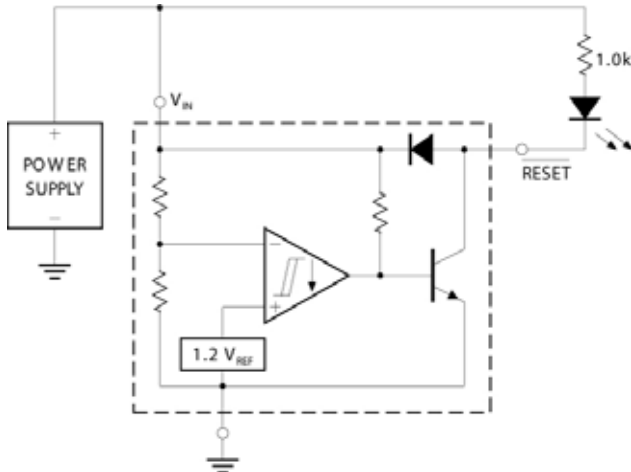


Figure 17 – Voltage Monitor

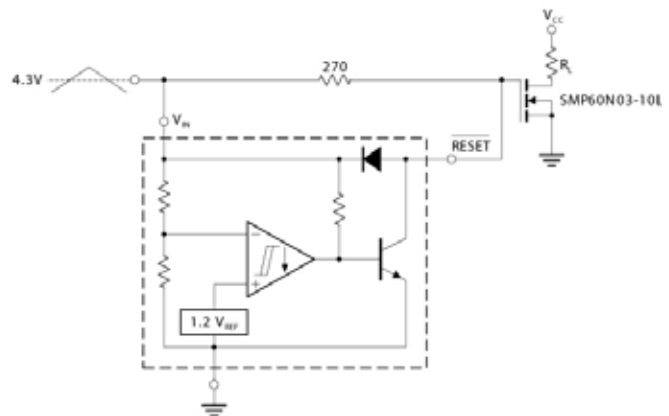


Figure 18 – MOSFET Low Voltage gate Drive Protection

Overheating of the logic level power MOSFET due to insufficient gate voltage can be prevented with the above circuit. When the input signal is below the 4.6 volt threshold of the MC34064, its output grounds the gate of the L² MOSFET.

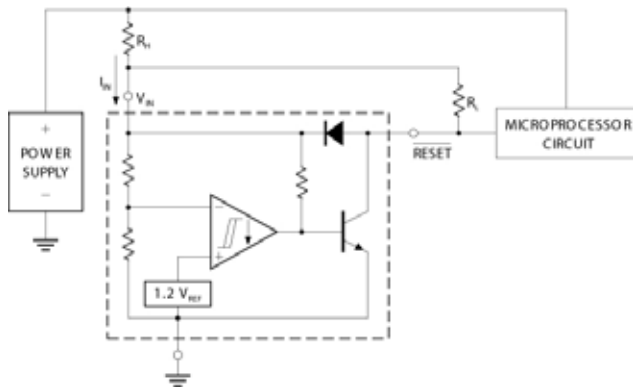
TYPICAL APPLICATION CIRCUITS


Figure 19 – Low Voltage Microprocessor Reset with Additional Hysteresis.

$$V_H = \frac{4.6R_H}{R_L} + 0.02$$

$$V_{TH(LOWER)} = 340R_H \cdot 10^{-6}$$

Where: $R_H = 150\Omega$
 $R_L = 1.5\Omega = 10k\Omega$

| Test Data | | | |
|-----------|----------------------|-----------------|-----------------|
| VH (mV) | ΔV_{TH} (mV) | RH (Ω) | RL (Ω) |
| 20 | 0 | 0 | 0 |
| 51 | 3.4 | 10 | 1.5 |
| 40 | 6.8 | 20 | 4.7 |
| 81 | 6.8 | 20 | 1.5 |
| 71 | 10 | 30 | 2.7 |
| 112 | 10 | 30 | 1.5 |
| 100 | 16 | 47 | 2.7 |
| 164 | 16 | 47 | 1.5 |
| 190 | 34 | 100 | 2.7 |
| 327 | 34 | 100 | 1.5 |
| 276 | 51 | 150 | 2.7 |
| 480 | 51 | 150 | 1.5 |

Comparator hysteresis can be increased with the addition of resistor R_H . The hysteresis equation has been simplified and does not account for the change of input current I_{IN} as V_{CC} crosses the comparator threshold. An increase of the lower threshold. $\Delta V_{TH(LOWER)}$ will be observed due to I_{IN} which is typically $340\mu A$ at $4.59V$. The equations are accurate to $\pm 10\%$ with R_H less than 150Ω and R_L between $1.5k\Omega$ and $10k\Omega$.

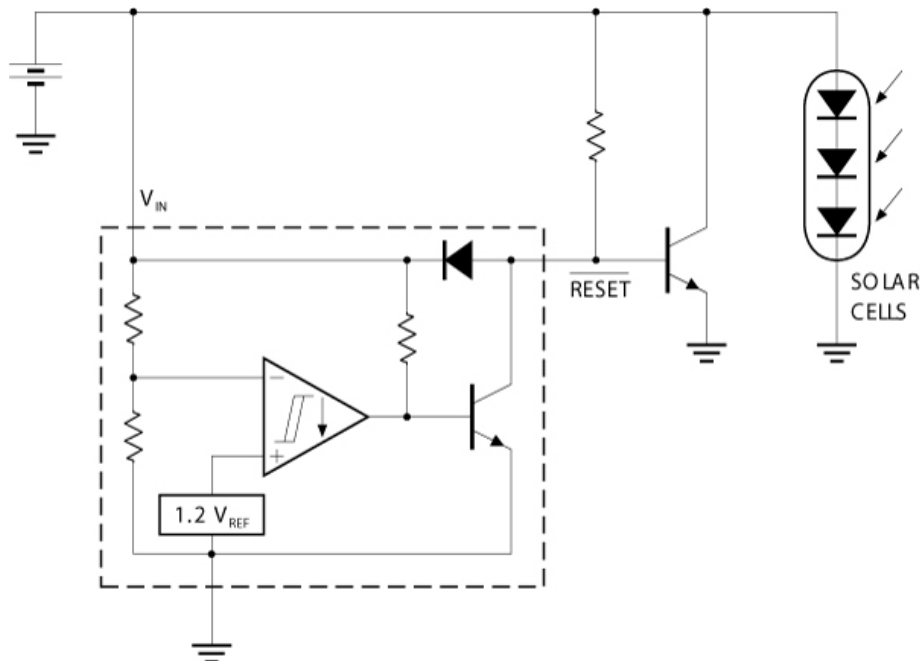


Figure 20 – Solar Powered Battery Charger



Microsemi[®]

TM

MC33064 / MC34064

Undervoltage Sensing Circuit

PRODUCTION DATA SHEET

NOTES

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